

## SCANNING ACOUSTIC MICROSCOPE

# VUE 250-P-NexGen

Semiconductor Package Failure Analysis  
voids · disbonds · cracks · delamination  
· internal defects



### Customer Interface

Dual 22" HD LED Monitors

### Fixtures

Open Tank Bed

### Instrumentation

Digital Pulsar Receiver  
Digitizer (Max 4 GHz)

### User Experience Elements

HD LED Lighting  
Stainless Steel Tank

### Maintenance Free Scan Axis

Motor: Linear Servo  
Max Velocity: 500 mm/s  
Accuracy & Repeatability: +/- 5.0 micron  
Scan Envelope: 322.6 mm

### Low Maintenance Step Axis:

Step Envelope 136 mm

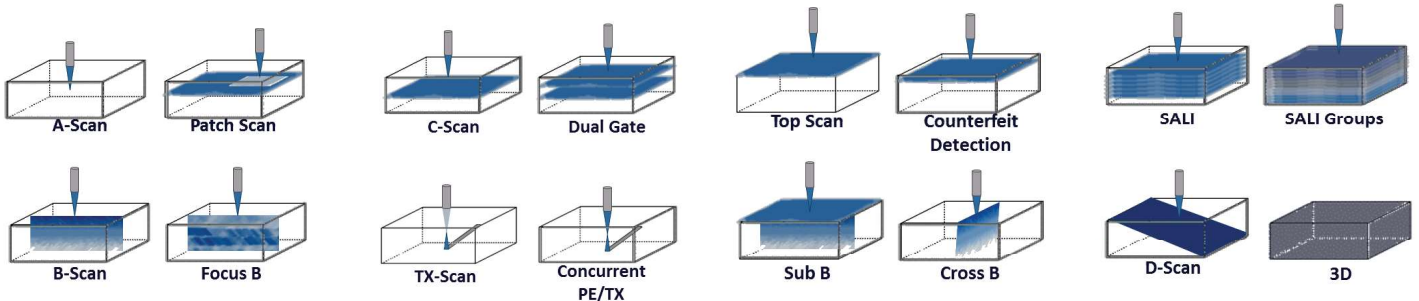
### Low Maintenance Focus Axis:

Focus Envelope 35 mm

### Dimensions:

700 mm x 560 mm x 470 mm (W/D/H)  
81 kg

## Full Jedec Tray Inspection

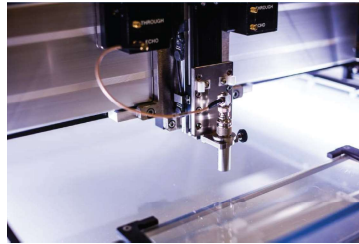


## GET IN TOUCH

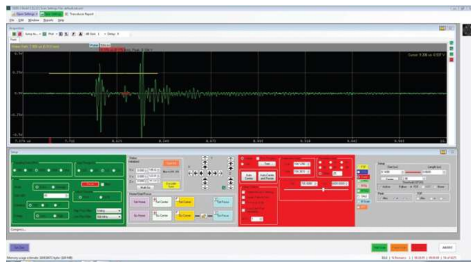
## OKOS Digital Imaging System (ODIS)

### Included Software Modes:

- Basic (user friendly)
- Advanced (detailed analysis)
- Production (automated scanning)
- Off-line Analysis (virtual scanning)



### OKOS Digital Imaging System (ODIS)



VUE 250-P imaging power surpasses modern standards delivering premium FA Lab features to semiconductor fabrication facilities. ODIS is the latest Acoustic Microscopy software with rich technical content built on current platforms and industry feedback. Advanced analysis is provided through quantitative tools for measurement and classification of parts.

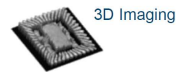
The Analysis version of ODIS allows non-scanning computers to virtually scan, view, and analyze data for simultaneous real-time analysis or post collection review.

- Counterfeit Detection
- Product Inspection
- Product Reliability
- Quality Control
- Process Validation
- Failure Analysis
- Vendor Qualification
- R&D

### Application Specific Transducers

for the highest quality resolution.

Multiple transducer design for enhanced scan capability.



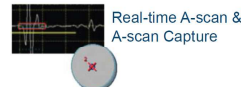
3D Imaging



C-scan with Multi-gate SALI & SALI Groups



Advanced Time-of-Flight & Thickness Measurements



Real-time A-scan & A-scan Capture



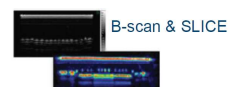
Void Gating (real-time)



Cluster Analysis (post processing)



Threshold Mapping (post processing)



B-scan & SLICE